

Toshiba Bipolar Linear Integrated Circuit  
Silicon Monolithic

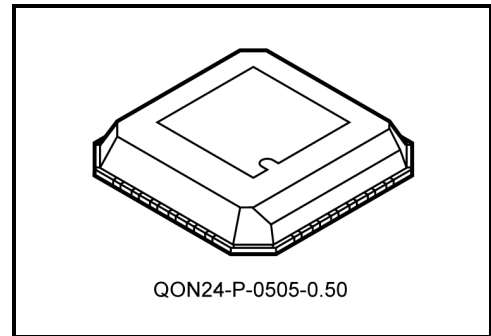
# TA8496FL

## Magnetic Head R/W IC

This IC enables writing and detection of magnetic recording signals.

### Features

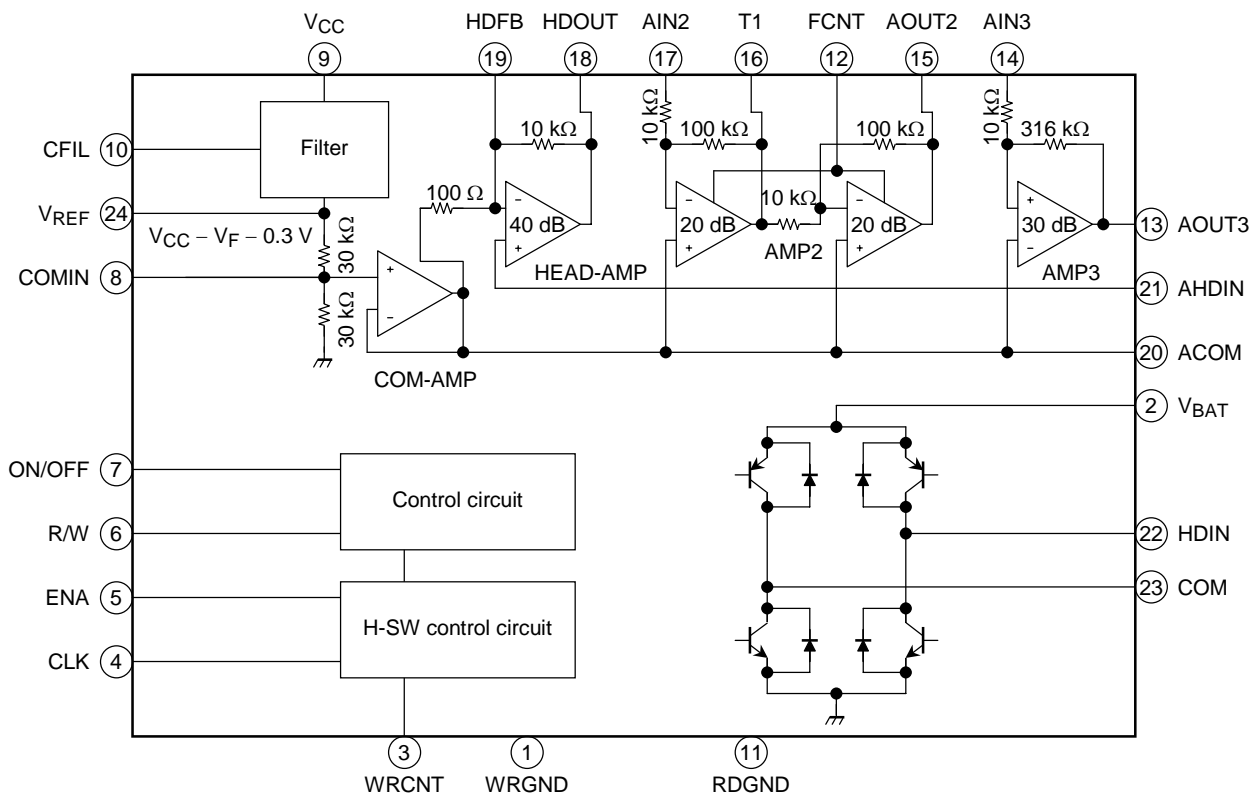
- Operating voltage range:  $V_{CC} = 3.5$  to  $7$  V  
 $V_{BAT} = 1.8$  to  $7$  V
- Output current:  $I_{out} = 20$  mA (max)
- Constant current operating function  
 $I_{OC} = (0.25 \text{ (V)} \times 160 \text{ (A)})/R_{WR}$  (typ.)



QON24-P-0505-0.50

Weight: 0.05 g (typ.)

### Block Diagram



## Pin Function

Pin Number	Symbol	Description
1	WRGND	GND for write block
2	V <sub>BAT</sub>	High-switch control power supply
3	WRCNT	Write output setting pin
4	CLK	High-switch operation control signal input
5	ENA	High-switch enable signal input
6	R/W	Read/write select signal input
7	ON/OFF	Chip enable signal input
8	COMIN	Internal reference voltage setting (fine adjustment)
9	V <sub>CC</sub>	Power supply input pin
10	CFIL	Power supply filter connecting pin (C = 0.1 μF)
11	RDGND	GND for read block
12	FCNT	Cut-off frequency setting pin
13	AOUT3	Amp 3 output
14	AIN3	Amp 3 input
15	AOUT2	Amp 2 output
16	T1	Amp 2 test pin
17	AIN2	Amp 2 input
18	HDOUT	Head amp output
19	HDFB	Head amp feedback input
20	ACOM	COM amp output
21	AHDIN	Head amp output
22	HDIN	Write output
23	COM	Write output
24	V <sub>ref</sub>	V <sub>CC</sub> filter output (internal power supply)

## Maximum Rating (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Power Supply Voltage	V <sub>CC</sub>	8	V
	V <sub>BAT</sub>	8	V
Input Voltage	V <sub>I</sub>	6	V
Output Current	I <sub>OUT</sub>	20	mA
Operating Temperature	T <sub>opr</sub>	-20 to 70	°C
Storage Temperature	T <sub>stg</sub>	-50 to 150	°C

## Recommended Operating Conditions

Characteristics	Symbol	Rating	Unit
Power Supply Voltage	V <sub>CC</sub>	3.5 to 7.0	V
	V <sub>BAT</sub>	1.8 to 7.0	

## Functions

Input				Write Unit		Read Unit
ON/OFF	R/W	ENA	CLK	COM	HDin	
H	H	H/L	H/L	$\infty$	$\infty$	Enable
	L	H	H	L	H	Disable
	L	H	L	H	L	Disable
	L	L	L	L	L	Disable
	L	L	H	$\infty$	$\infty$	Disable
L	H/L	H/L	H/L	$\infty$	$\infty$	Disable

$\infty$ : High impedance

## Electrical Characteristics

Interface Block (unless otherwise is specified,  $V_{CC} = 5\text{ V}$ ,  $V_{BAT} = 3\text{ V}$ ,  $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Input Voltage	$V_{IN1-Hi}$	—	ENA, ON/OFF	2.5	—	$V_{CC}$	V
	$V_{IN1-Lo}$	—	ENA, ON/OFF	—	—	1.0	
	$V_{IN2-Hi}$	—	CLK, R/W	1.5	—	$V_{CC}$	
	$V_{IN2-Lo}$	—	CLK, R/W	—	—	0.5	
Input Current	$I_{IN1-Hi}$	1	CLK, $V_{IN} = 5\text{ V}$	—	15	25	$\mu\text{A}$
	$I_{IN1-Lo}$		CLK, $V_{IN} = 0\text{ V}$	—	-85	-120	
	$I_{IN2-Hi}$		ENA, $V_{IN} = 5\text{ V}$	—	85	120	
	$I_{IN3-Hi}$		R/W, $V_{IN} = 5\text{ V}$	—	15	25	
	$I_{IN3-Lo}$		R/W, $V_{IN} = 0\text{ V}$	—	-85	-120	
	$I_{IN4-Hi}$		ON/OFF, $V_{IN} = 5\text{ V}$	—	85	120	

### Read Block (unless otherwise is specified, $V_{CC} = 5\text{ V}$ , $V_{BAT} = 3\text{ V}$ , $T_a = 25^\circ\text{C}$ )

Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Current Dissipation		$I_{CCR}$	2	When read block in operation	—	3.2	4.6	mA
		$I_{CCO}$		When chip disabled (on/off = low or open)	—	0	1	$\mu\text{A}$
Gain Characteristics	Head amp	$G_H$	3	—	—	40	—	dB
	Amp 2	$G_2$		—	—	40	—	
	Amp 3	$G_3$		—	—	30	—	
Head Amp Input Conversion Noise		$E_{n1}$	—	$R_g = 0\ \Omega$ , $f_c = 19\ \text{kHz}$	—	0.33	(0.64)*	$\mu\text{V}_{\text{rms}}$
		$E_{n2}$		$R_g = 0\ \Omega$ , $f_c = 1.7\ \text{kHz}$	—	0.15	(0.26)*	
Reference Voltage		$V_{ACOM}$	3	—	1.9	2.0	2.1	V
Output Offset Voltage	Head amp	$V_{HOS}$	3	—	—	-0.1	$\pm 0.25$	V
	Amp 2	$V_{2OS}$			—	+0.7	$\pm 1.1$	
	Amp 3	$V_{3OS}$			—	+0.1	$\pm 0.25$	
Amp 3 Output Voltage Range	Low	$V_{3OL}$	4	$R_L = 10\ \text{k}\Omega$	—	0.2	—	V
	High	$V_{3OH}$			—	4.1	—	
Amp 3 Output Current	Output	$I_{3OUT}$	4	—	2.0	—	—	mA
	Input	$I_{3IN}$		—	0.1	0.2	0.3	

\*: Guaranteed by design. Determined at design and does not change at manufacturing. Test not conducted.

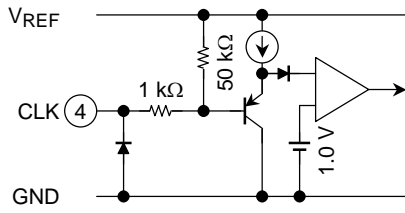
### Write Block (unless otherwise is specified, $V_{CC} = 5\text{ V}$ , $V_{BAT} = 3\text{ V}$ , $T_a = 25^\circ\text{C}$ )

Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit	
Current Dissipation		$I_{CCw}$	2	During write, CLK = Low/High	—	3.7	5.2	mA	
		$I_{CCe}$		When write enabled	—	1.9	2.8		
		$I_{CCB}$		When write in break	—	4.4	6.1		
		$I_{bat}$		During write, reactive current ( $R_{WR} = 5\ \text{k}\Omega$ )	—	1.4	1.8		
		$I_{baB}$		When write in break	—	1.0	1.6	$\mu\text{A}$	
		$I_{bar}$		During read	—	0	1		
		$I_{bao}$		When chip disabled (on/off = low or open)	—	0	1		
Set Output Current		$I_{OC}$	5	$I_{OC} = 10\ \text{mA}$ (at $V_{BAT} = 2.0\ \text{V}$ )	$V_{BAT} = 2.0\ \text{V}$	8	10	12	mA
				$V_{BAT} = 5.0\ \text{V}$	—	11	13		
CLK Output Transfer Time		$T_{pLH1}$	6	0 to 10% (Note1)	—	0.1	—	$\mu\text{s}$	
		$T_{pLH2}$		0 to 90% (Note1)	—	0.5	—		
		$T_{pHL1}$		0 to 10% (Note1)	—	0.1	—		
		$T_{pHL2}$		0 to 90% (Note1)	—	0.5	—		
ENA Output Transfer Time		$T_{pZH1}$	6	0 to 10% (Note1)	—	0.3	—	$\mu\text{s}$	
		$T_{pZH2}$		0 to 90% (Note1)	—	0.5	—		
		$T_{pHZ1}$		0 to 10% (Note1)	—	0.3	—		
		$T_{pHZ2}$		0 to 90% (Note1)	—	0.5	—		

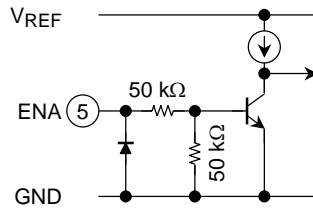
Note 1: Load  $R_L = 36\ \Omega$ ,  $C_L = 10\ \text{pF}$

## Input/Output Circuit

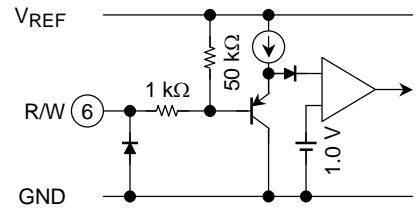
- CLK pin



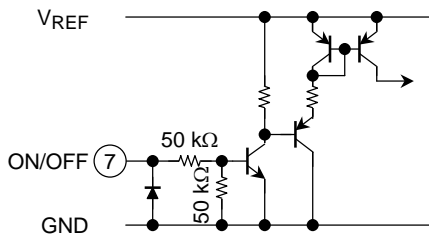
- ENA pin



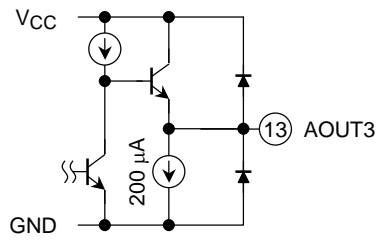
- R/W pin



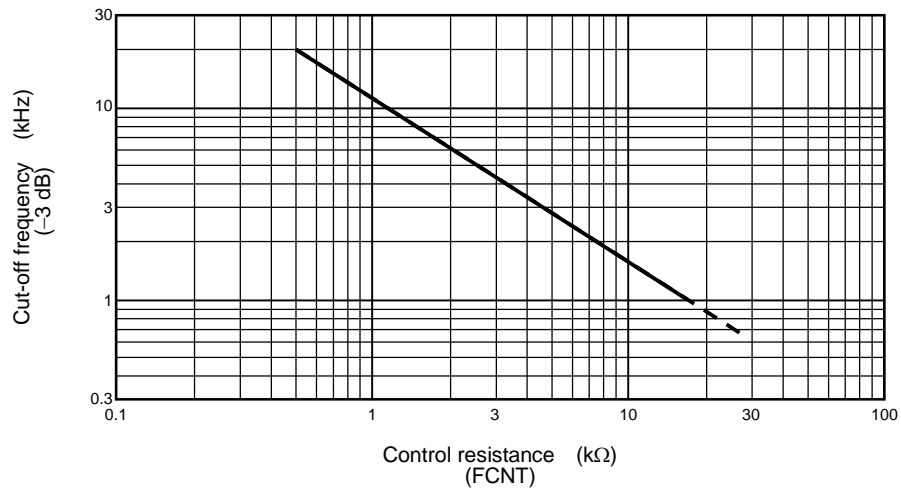
- ON/OFF pin



- AOUT3 pin

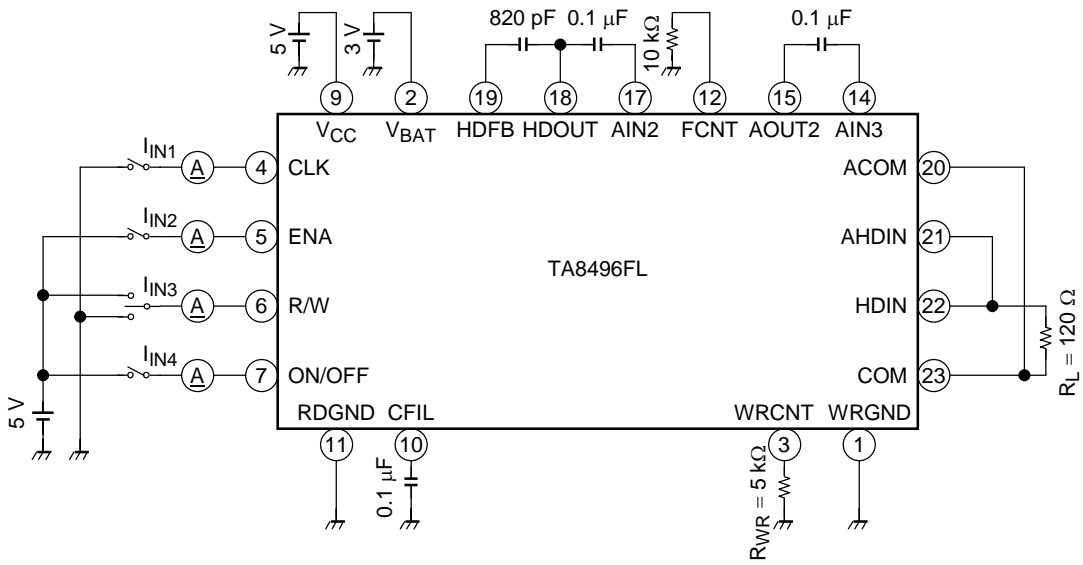


Secondly L.P.F characteristics (amp 2)

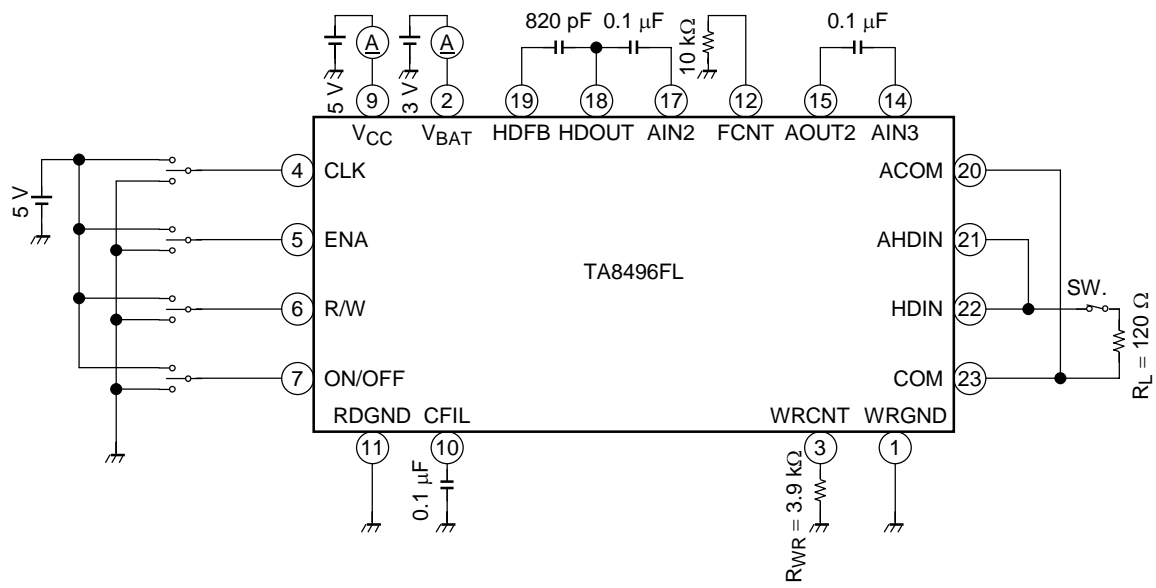


**Test Circuit**

**1. Input Current ( $I_{IN1}$ ,  $I_{IN2}$ ,  $I_{IN3}$ ,  $I_{IN4}$ )**



**2. Current Consumption ( $I_{CCR}$ ,  $I_{CCO}$ ,  $I_{CCW}$ ,  $I_{CCe}$ ,  $I_{CCB}$ ,  $I_{bat}$ ,  $I_{baB}$ ,  $I_{bar}$ ,  $I_{bao}$ )**

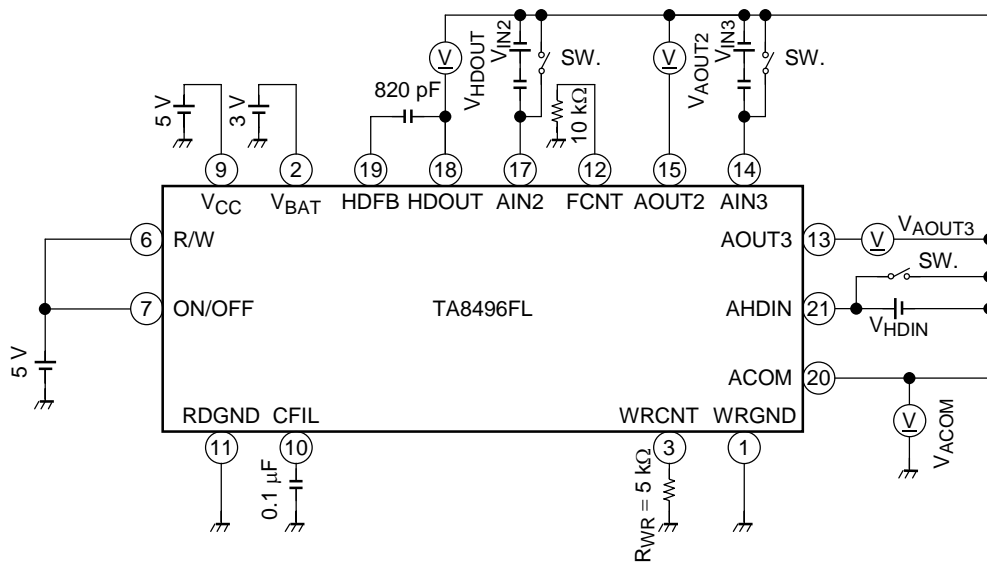


**Input Sequence (H = 5 V, L = 0 V)**

Current Consumption ( $V_{CC}$ , $V_{BAT}$ )	ON/OFF	R/W	ENA	CLK
$I_{CCR}$	H	H	L	H
$I_{CCO}$	L/OPEN	H	H/L	H
$I_{CCW}$	H	L	H	H/L
$I_{CCe}$	H	L	L	H
$I_{CCB}$	H	L	L	L
$I_{bat}$ (Note2)	H	L	H	H/L
$I_{baB}$	H	L	L	L
$I_{bar}$	H	H	H/L	H/L
$I_{bao}$	L/OPEN	H/L	H/L	H/L

Note 2: SW. OFF

**3. Gain Characteristics ( $G_H$ ,  $G_2$ ,  $G_3$ ), Power Off-Set Voltage ( $V_{HOS}$ ,  $V_{2OS}$ ,  $V_{3OS}$ )**

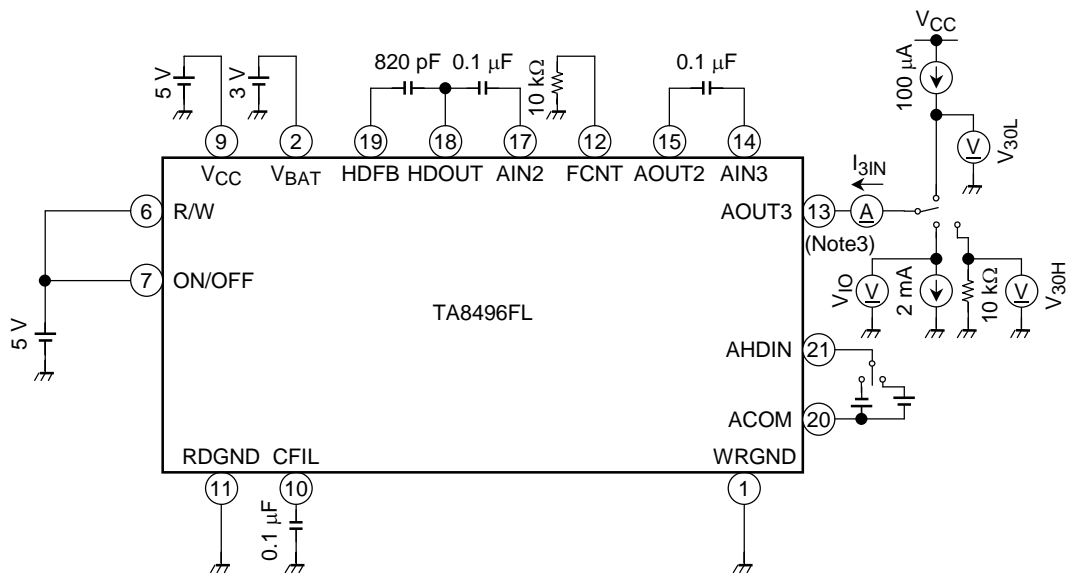


$$G_H = 20 \log \left| \frac{V_{HDOUT}}{V_{HDIN}} \right|, \quad G_2 = 20 \log \left| \frac{V_{AOUT2}}{V_{IN2}} \right|, \quad G_3 = 20 \log \left| \frac{V_{AOUT3}}{V_{IN3}} \right|$$

When off-set voltage is measured, SW turns ON.

$$V_{HOS} = |V_{HDOUT}|, \quad V_{2OS} = |V_{AOUT2}|, \quad V_{3OS} = |V_{AOUT3}|$$

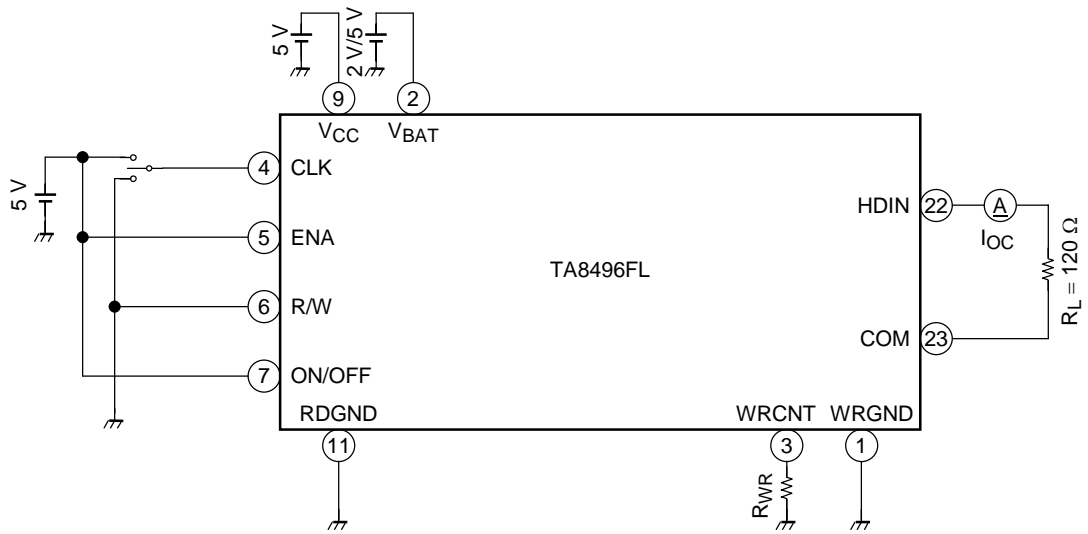
**4. Amp 3 Output Voltage Range ( $V_{30L}$ ,  $V_{30H}$ ), Amp 3 Output Current ( $I_{3OUT}$ ,  $I_{3IN}$ )**



Note 3:  $I_{3OUT}$  must be measured on condition in  $V_{IO} \geq 4.0$  V

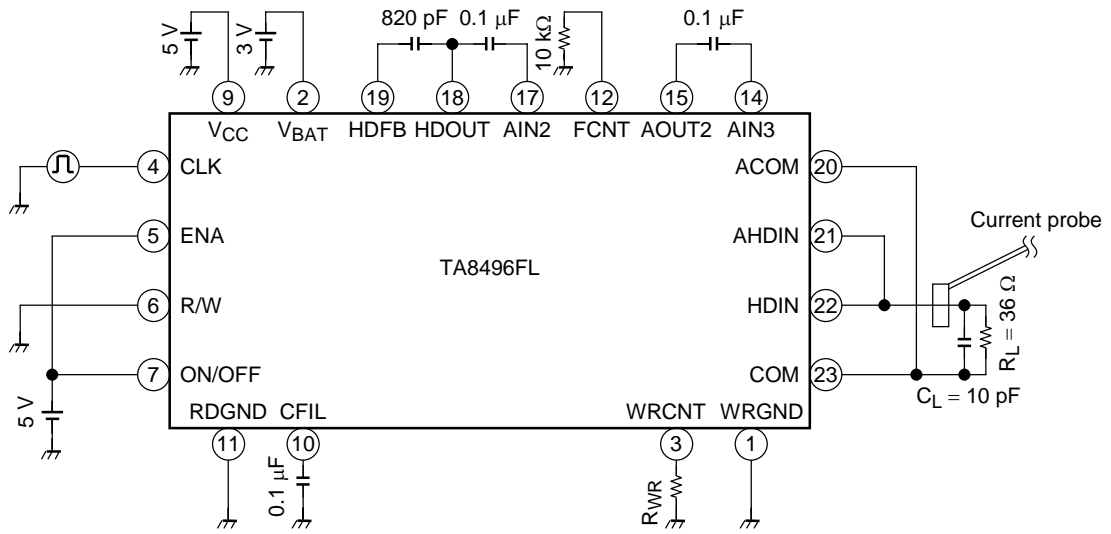


**5. Set Output Current ( $I_{OC}$ )**

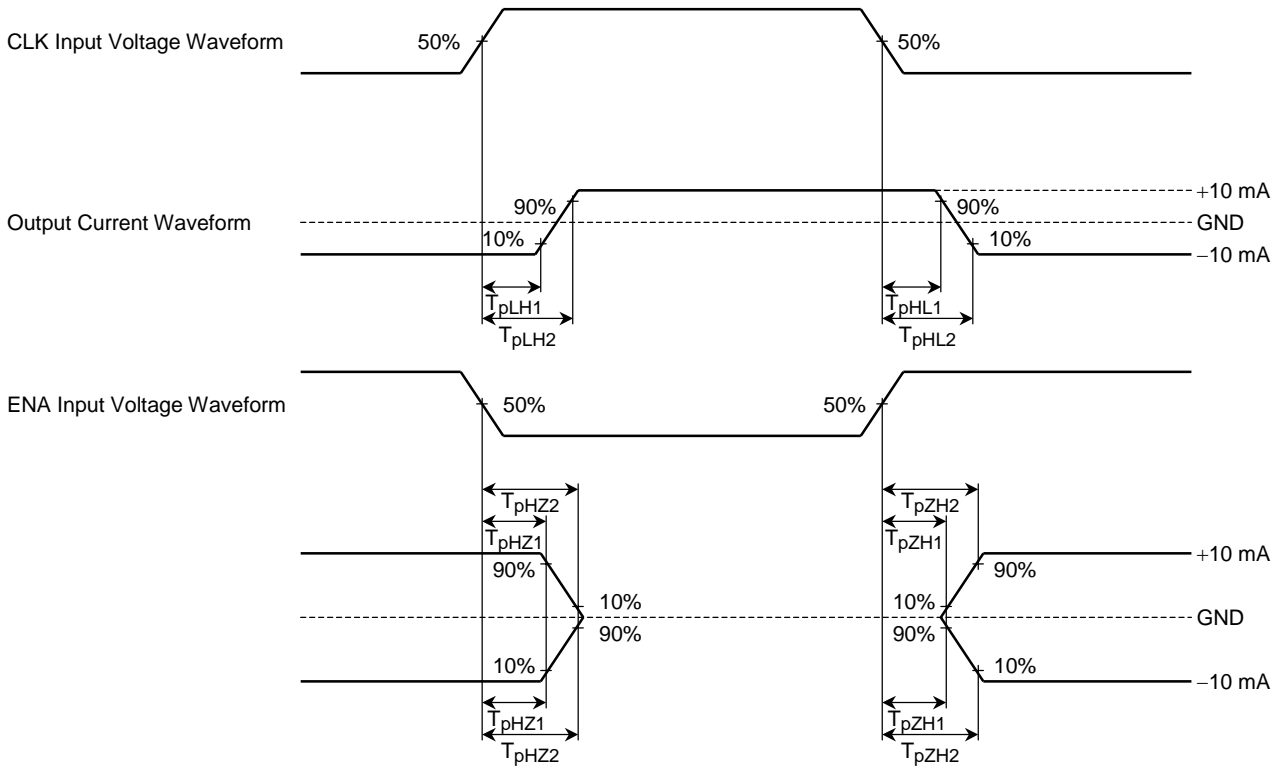


Set  $R_{WR}$  so that  $I_{OC} = 10 \text{ mA}$  (at  $V_{BAT} = 2 \text{ V}$ ).  
 At this time, due to fluctuation in samples,  $I_{OC}$  fluctuates in the range of 8 to 12 mA. Also,  $I_{OC}$  fluctuates depending on the power supply ( $V_{BAT}$ ) as follows:  $I_{OC} = 10 \text{ mA}$  (at  $V_{BAT} = 2 \text{ V}$ )  $\rightarrow$   $I_{OC} \approx 13 \text{ mA}$  (at  $V_{BAT} = 5 \text{ V}$ ).

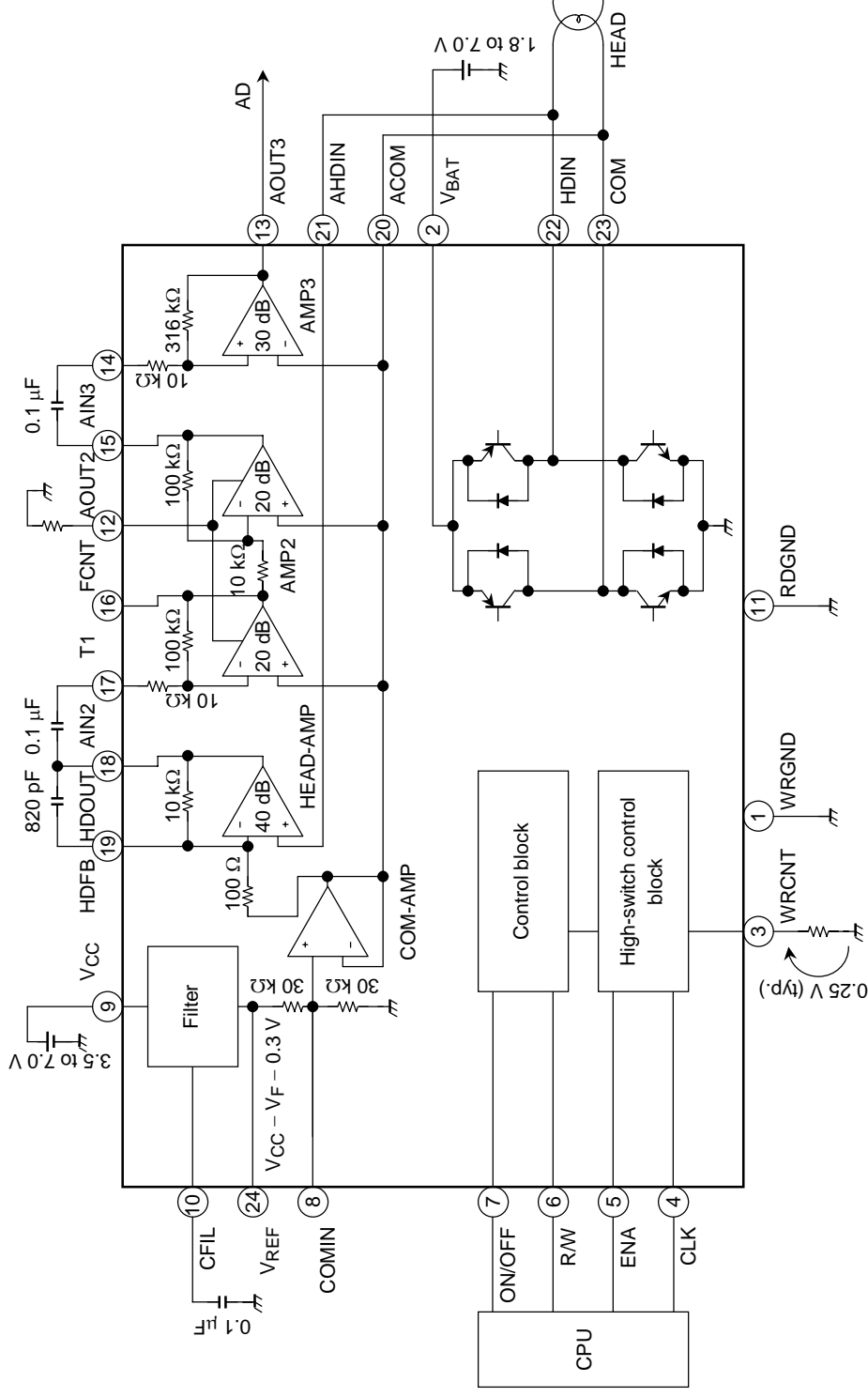
**6. CLK, ENA Output Propagation Time ( $T_{pLH1/2}$ ,  $T_{pHL1/2}$ ,  $T_{pZH1/2}$ ,  $T_{pHZ1/2}$ )**



RWR: I<sub>OC</sub> is set 10 mA.



**Example of Application Circuit**



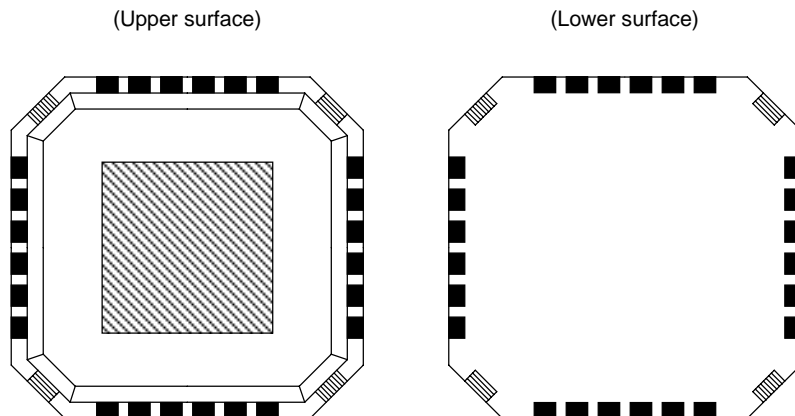
Note 4: Operating supply voltage range

$V_{CC} = 3.5 \text{ to } 7.0 \text{ V}$ ,  $V_{BAT} = 1.8 \text{ to } 7.0 \text{ V}$   
 However, set  $V_{CC}$  so that  $V_{ACOM} \leq V_{BAT} + 0.5 \text{ V}$ .  $V_{CC} \geq V_{BAT}$ .  
 $(V_{ACOM} = (V_{CC} - V_F - 0.3)/2)$   
 By connecting a resistor to the COMIN pin,  $V_{ACOM}$  can be varied.

Note 5: The IC may be damaged by shorts between pins, to the power supply, or to ground. Take great care when designing lines.

## Requests Concerning Use of QON

### Outline Drawing of Package



When using QON, please take into account the following items.

#### Caution

- (1) Do not carry out soldering on the island section in the four corners of the package (the section shown on the lower surface drawing with diagonal lines) with the aim of increasing mechanical strength.
- (2) The island section exposed on the package surface (the section shown on the upper surface drawing with diagonal lines) must be used as (Note 6) below while electrically insulated from outside.

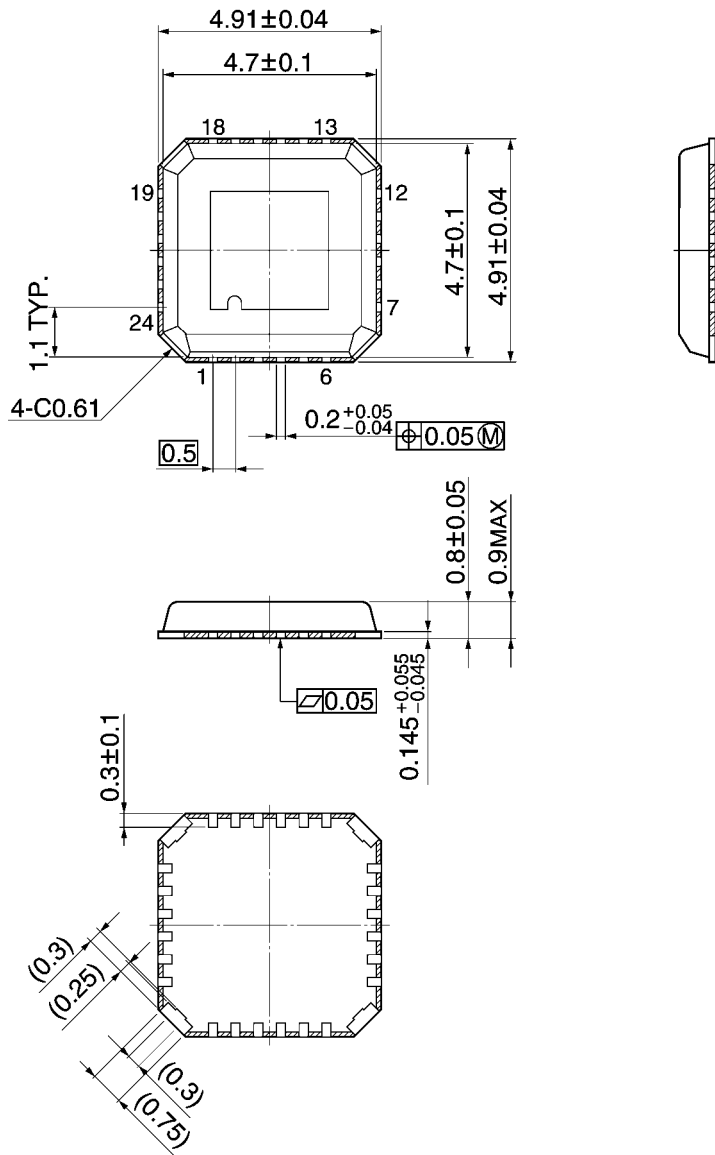
Note 6: Ensure that the island section (the section shown on the lower surface drawing with diagonal lines) does not come into contact with solder from through-holes on the board layout.

- When mounting or soldering, take care to ensure that neither static electricity nor electrical overstress is applied to the IC (measures to prevent anti-static, leaks, etc.).
- When incorporating into a set, adopt a set design that does not apply voltage directly to the island section.

## Package Dimensions

QON24-P-0505-0.50

Unit: mm



Note 1) The solder plating portion in four corners of the package shall not be treated as an external terminal.

Note 2) Don't carry out soldering to four corners of the package.

Note 3)  area : Resin surface

Weight: 0.05 g (typ.)

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000707EBA

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